

MODEL NO. :	TM030LBHT1
SSUED DATE: _	2012-05-08
VERSION : _	Ver 2.0

□Preliminary Specification■ Final Product Specification

**Customer:** 

Approved by	Notes

## **SHANGHAI TIANMA Confirmed:**

prepared by	Checked by	Approved by

This technical specification is subjected to change without notice



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## **Record of Revision**

Rev	Issued Date	Description	Editor
2.0	2012-05-08	Final Product Specification	LONGPING.DENG



## 1 General specifications

	Fe	Spec			
	Size		3.0 inch		
	Resolution	n	240(RGB) X 400		
	Interface		RGB+3SPI/CPU		
	Color De	pth	262K		
	Technolo	gy type	a-si TFT		
Diamless Chas	Pixel pitc	h (mm)	0.162x0.162		
Display Spec.	Pixel Cor	nfiguration	R.G.B. Vertical Stripe		
	Display N	/lode	ECB Mode Transflective		
	Surface 7	Freatment(Up Polarizer)	Clear type (3H)		
	Surface 7	Freatment(TSP)	Without TSP		
	Viewing I	Direction	6 o'clock		
	Gray Sca	le Inversion Direction	12 o'clock		
	DIM.	LCM (W x H x D) (mm)	47.28x76.4x2.4		
	Active Ar	ea(mm)	38.88x 64.8		
Mechanical Characteristics	With /Wit	hout TSP	WithTSP		
	Weight (g	gram)	28.35g		
	LED Nun	nbers	4LEDs (serial)		

Note 1 : Viewing direction for best image quality is different from TFT definition, there is a 180 degree shift.

Note 2: Requirements on Environmental Protection: Q/S0002



## 2 Input/Output terminals

Pin	Symbol (CPU)	Symbol (RGB)	I/O	Description	Remark
1	GND	GND		Ground	
2	LED-K	LED-K		Power supply for LED(Low voltage)	
3	LED-A2	LED-A2		Power supply for LED(High voltage2)	
4	LED-A1	LED-A1		Power supply for LED(High voltage1)	
5	GND	GND		Ground	
6	GND	GND		Ground	
7	/RESET	/RESET	I	RESET serial(Low active)	
8	GND	GND		Ground	
9	DB17	R5	I/O	CPU:Data bus serial(MSB) RGB:RED data signal(MSB)	
10	DB16	R4	I/O	CPU:Data bus serial RGB:RED data signal	•
11	DB15	R3	I/O	CPU:Data bus serial RGB:RED data signal	
12	DB14	R2	I/O	CPU:Data bus serial RGB:RED data signal	
13	DB13	R1	I/O	CPU:Data bus serial RGB:RED data signal	
14	DB12	R0	I/O	CPU:Data bus serial RGB:RED data signal(LSB)	
15	DB11	G5	I/O	CPU:Data bus serial RGB:GREEN data signal(MSB)	
16	DB10	G4	I/O	CPU:Data bus serial RGB:GREEN data signal	
17	DB9	G3	1/0	CPU:Data bus serial RGB:GREEN data signal	
18	DB8	G2	I/O	CPU:Data bus serial RGB:GREEN data signal	
19	DB7	G1	I/O	CPU:Data bus serial RGB:GREEN data signal	
20	DB6	G0	I/O	CPU:Data bus serial RGB:GREEN data signal(LSB)	
21	DB5	B5	I/O	CPU:Data bus serial RGB:BLUE data signal(MSB)	
22	DB4	B4	I/O	CPU:Data bus serial RGB:BLUE data signal	
23	DB3	B3	I/O	CPU:Data bus serial RGB:BLUE data signal	
24	DB2	B2	I/O	CPU:Data bus serial RGB:BLUE data signal	
25	DB1	B1	I/O	CPU:Data bus serial RGB:BLUE data signal	
26	DB0	В0	I/O	CPU:Data bus serial RGB:BLUE data signal(LSB)	



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27	GND	SDI	I	CPU: Ground RGB: Serial data input pin			
				CPU: not use. leave open or to			
28	OPEN	SDO	0	GND/VCCIO			
				RGB: Serial data output pin			
29	/RD	NC	ı	CPU: read signal and read data.			
				RGB: NO connect			
30	/WR	NC	I	CPU: write signal and write data. RGB: NO connect			
31	RS	SCL	ı	CPU: Data / Command Selection pin.			
31	_		ı	RGB: Serial Clock signal			
32	/CS	CS	I	Chip select signal.			
33	GND	ENABLE	ENABLE   CPU: Ground				
	OND	LIVIULE I		RGB: A data ENABLE signal			
34	GND	VSYNC I		CPU: Ground			
						RGB: Frame synchronizing signal	
35	GND	HSYNC I		CPU: Ground RGB: Frame synchronizing signal			
-				CPU: Ground			
36	GND	DOTCLK	I	RGB: Pixel clock signal			
				CPU: Tearing effect output.			
37	TE	TE	0	RGB: Not used, please open this pin.			
38	VCCIO	VCCIO	Р	I/O Pad and Digital power supply			
39	VCC	VCC	Р	Analog power supply			
40	IM0/1D	IM0/1D	I	System interface select.	Note2		
41	IM1	IM1	1 (	System interface select.	Note2		
42	IM2	IM2		System interface select.	Note2		
43	GND	GND		Ground			
44	GND	GND		Ground			
45	GND	GND		Ground			

Note1: P: Power/GND; I: input pin; O: output Note2:System interface select

IM3	IM2	IMO	Interface			
0	0	0	8080 MCU 18-bits Parallel II			
0	1	0	8080 MCU 16-bits Parallel II			
0	0	1	8080 MCU 9-bits Parallel II			
0	1	1	8080 MCU 8-bits Parallel II			
1	0	ID	3-wire Serial interface			
1	1	0	4-wire Serial interface(1)			
1	1	1	SPI(2),HSIM Interface			



## 3 Absolute maximum ratings

Item	Symbol	MIN	MAX	Unit	Remark
Supply Voltage	VCC	-0.3	4.6	V	
Supply Voltage	VCCIO	-0.3	4.6	V	
Input voltage	D[17: 0], CS, RD, WR, RS/SCL, SDI, VSYNC, HSYNC, DOTCLK, ENABLE, BS[2:0]	-0.3	VCC+0.3	V	
Back Light Forward Current	I <sub>LED</sub>		25	mA	For each LED
Operating Temperature	$T_OPR$	-20	70	$^{\circ}$	
Storage Temperature	T <sub>STG</sub>	-30	80	$^{\circ}$ C	

(GND=0, Ta = 25°C)

## 4 LCD module electrical characteristics

## 4.1 Driving TFT LCD Panel

Item		Symbol	MIN	TYP	MAX	Unit	Remark
Supply \	/oltage	VCC	2.5	2.8	3.3	V	
Supply \	/oltage	IOVCC	1.65	2.8	3.3	V	
Input Signal Low Level		V <sub>IL</sub>	-0.3		0.2* IOVCC	V	
Voltage	High Level	V <sub>IH</sub>	0.8* IOVCC		IOVCC	٧	
Output Signal	Low Level	V <sub>OL</sub>	-0.3		0.3* IOVCC	V	
Voltage	High Level	V <sub>ОН</sub>	0.7* IOVCC		IOVCC	٧	
(Panel+LSI)		Black Mode (60Hz)		TBD		mW	
Power Consu	ımption	8 color Mode		TBD		mW	
		Standby Mode		TBD		mW	

(GND=0,Ta=25°C)

## 4.2 Backlight Unit Driving Condition

(GND=0,Ta=25°C)

Parameter	Symbol	MIN	TYP	MAX	Unit	Remark
Forward Current	I <sub>F</sub>	-	20	-	mA	Note 1
Forward Voltage	V <sub>F</sub>	-	12.8	-	V	Note 2
Backlight Power	W <sub>BL</sub>	-	256	-	mW	

Note 1: The LED driving condition is defined for each LED module.

Note 2: Backlight unit driving must depend on Forward Current setting.

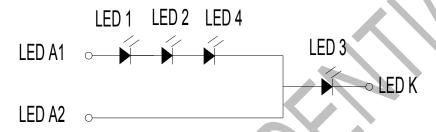
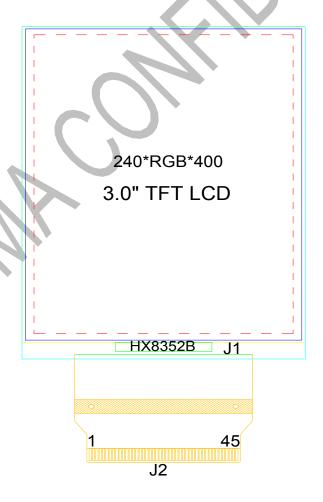


Fig.4-1 LED connection of backlight

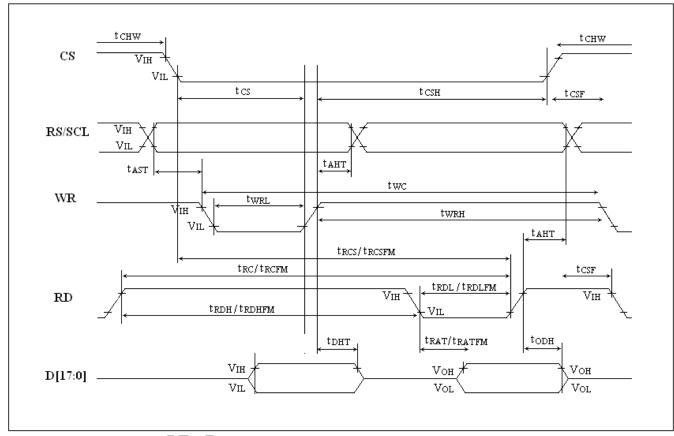
## 4.3 Block Diagram



## 5 AC ELECTRICAL CHARACTERISTICS

#### 5.1 CPU interface mode

#### 5.1.1 CPU Interface Characteristics



**CPU Interface Characteristics** 



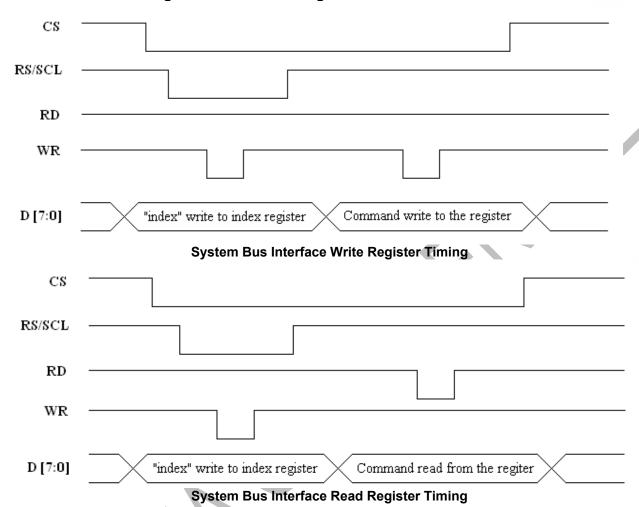
## 5.1.2 CPU Interface Timing Parameters

Normal Write Mode (IOVCC=1.65~3.3V, VCC=2.3~3.3V)

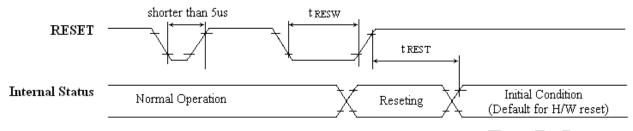
		Peremeter		Spec.		Description	
Signal	Symbol	Parameter	Min.	Max.	Unit	Description	
RS/SCL	RS/SCL t <sub>AST</sub> Address setup time		10 10	-	ns	-	
CS	taht tchw tcs trcs trcsfm tcsf tcsh	Address hold time(Write/Read) Chip select "H" pulse width Chip select setup time (Write) Chip select setup time (Read ID) Chip select setup time (Read FM) Chip select wait time(Write/Read) Chip select hold time	0 35 100 100 10 10	-	ns		
WR	t <sub>wc</sub> t <sub>wrh</sub> t <sub>wrl</sub>	Write cycle Control pulse "H" duration Control pulse "L" duration	100 20 20	-	ns	-	
RD	t <sub>RC</sub> t <sub>RDH</sub> t <sub>RDL</sub>	Read cycle (ID) Control pulse "H" duration (ID) Control pulse "L" duration (ID)	150 40 50	-	ns	When read ID data	
RD	t <sub>RCFM</sub> t <sub>RDHFM</sub> t <sub>RDLFM</sub>	Read cycle (FM) Control pulse "H" duration (FM) Control pulse "L" duration (FM)	250 50 150 20	_	ns	When read from frame memory	
D[17:0]	tdst tdht trat tratfm todh	t <sub>DHT</sub> Data hold time t <sub>RAT</sub> Read access time (ID) t <sub>RATFM</sub> Read access time (FM)		- 70 100 80	ns	For maximum $C_L$ =30pF For minimum $C_L$ =8pF	

**CPU Interface Timing Parameters** 

#### 5.1.3 CPU Interface Register write/read timing



## 5.2 Reset Timing



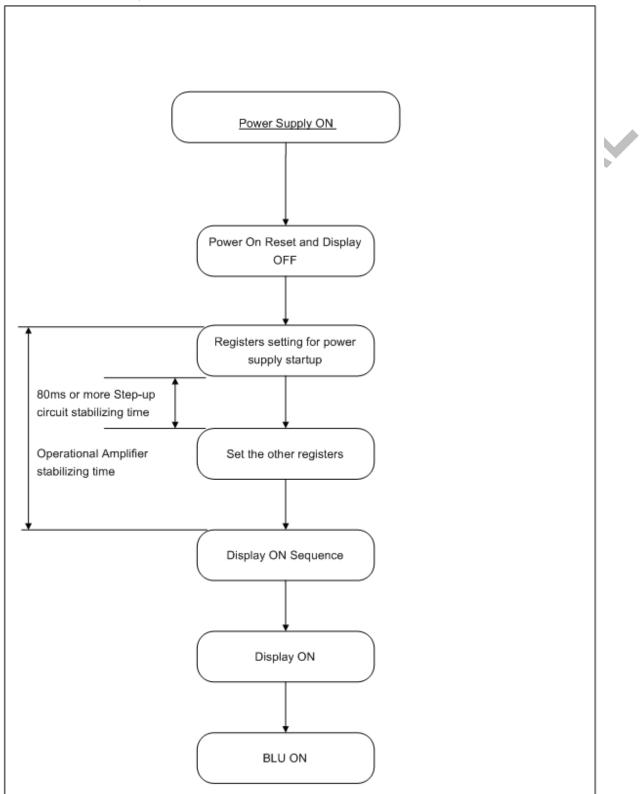
**Reset timing** 

Reset input timing

0	B	Related	Spec.			Ninte	
Symbol	Parameter	Pins	Min.	Тур.	Max.	Note	Unit
t <sub>RESW</sub>	Reset low pulse width	RESET	10	-		-	us
<b>t</b> REST	Reset complete	-	-	-	5	When reset applied during "Sleep In mode"	ms
	time	-			When reset applie 120 during "Sleep Out	When reset applied during "Sleep Out mode"	ms

## POWER ON/OFF SEQUENCE

#### 6.1 POWER ON SEQUENCE



Normal Display **BLU OFF** Display OFF Sequence Display OFF Power Supply Halt Setting Power Supply OFF (VDD)



## Optical characteristics

## 7.1 Driving the backlight condition

Ta=25°C

Item		Symbol	Condition	Min	Тур.	Max.	Unit	Remark
View Angles		⊖Т	- CR≥10 -	-	55	60	Degree	Note 2
		⊖В		-	40	45		
		θL		-	40	45		
		$\theta$ R		-	45	50		
Contrast Ratio		CR	θ=0°	80	100	-		Note1 Note3
Response Tim	Δ	Ton	<b>25</b> ℃	_ 3/	35		ms	Note1
ixesponse rim	Response Time		250	1	35		1115	Note4
Chromaticity	White	X	θ=0°	-	0.30	-		Note5,
Chilomaticity	VVIIILE	у	0 -0	-	0.33	-		Note1
Luminance		L		110	130	-	cd/m <sup>2</sup>	Note1 Note7

#### 7.2 Not Driving the backlight condition

Ta=25°C

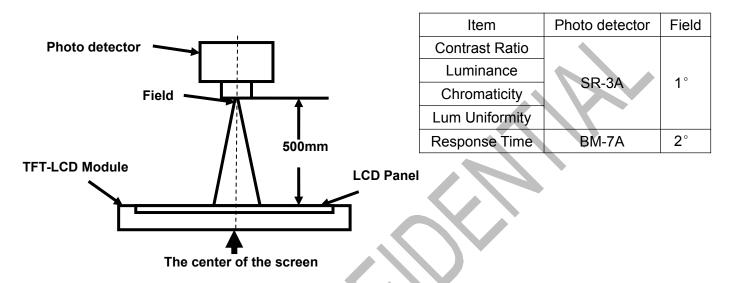
Item	Symbol	Condition	Min	Тур.	Max.	Unit	Remark
	⊖Т			60	-		
Minus Anglan	⊖В	CR≧10 -	-	60	-	Degree	Note 2
View Angles	θL		-	55	-		
	$\theta$ R		-	60	-		
Contrast Ratio	CR	θ=0°	-	8	-		Note1 Note3
Response Time	Ton Toff	<b>25</b> ℃	-	25	-	ms	Note1 Note4
	X	0.00	-	0.32	-		Note5,
Chromaticity White	у	$\theta = 0^{\circ}$	-	0.34	-		Note1
Luminance	L		110	130	-	cd/m <sup>2</sup>	Note1 Note7
Reflection ratio				6.85%			

## **Test Conditions:**

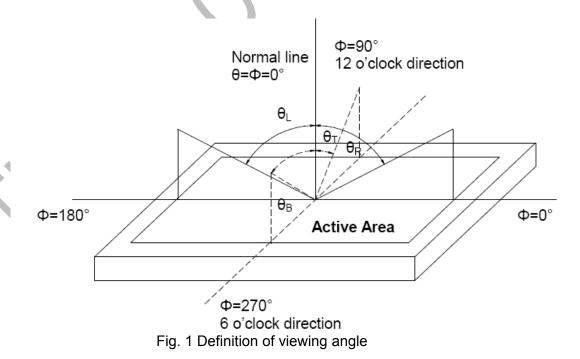
- 1. VDD=2.8V, I<sub>L</sub>=20mA( LED current), the ambient temperature is 25℃.
- 2. The test systems refer to Note 1, Note 2 and Note 8.

Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system. viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).



Note 3: Definition of contrast ratio

Contrast ratio (CR) = Luminance measured when LCD is on the "White" state

Luminance measured when LCD is on the "Black" state

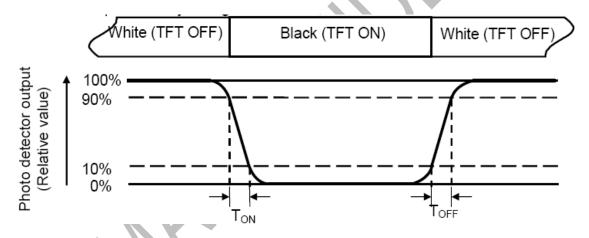
"White state ":The state is that the LCD should driven by Vwhite.

"Black state": The state is that the LCD should driven by Vblack.

Vwhite: To be determined Vblack: To be determined.

## Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time (TON) is the time between photo detector output intensity changed from 90% to 10%. And fall time (TOFF) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

#### Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity(U) = Lmin/Lmax

L-----Active area length W----- Active area width

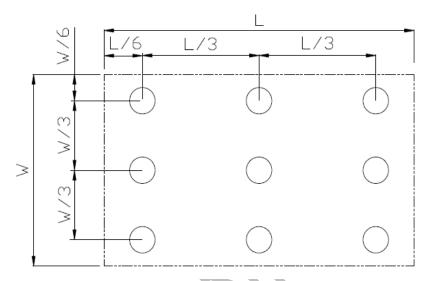


Fig. 2 Definition of uniformity

Lmax: The measured maximum luminance of all measurement position.

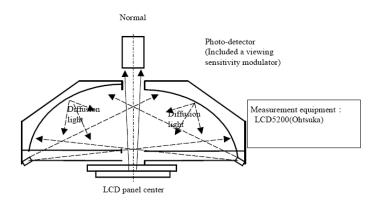
Lmin: The measured minimum luminance of all measurement position.

## Note 7: Definition of Luminance:

Measure the luminance of white state at center point.

## Note 8: Definition of Reflectance measurement system

Note 5) Reflectance is defined as follows:





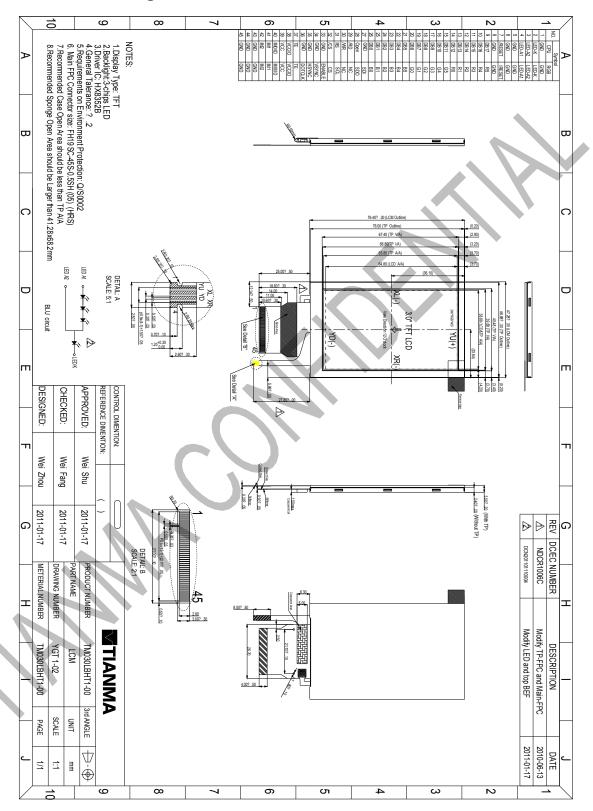
## B Environmental / Reliability tests

No	Test Item	Condition	Remarks
1	High Temperature Operation	•	Note1 IEC60068-2-2,GB2423.2
2	Low Temperature Operation	Ta=-20°C, 240hrs	IEC60068-2- GB2423.1
3	High Temperature Storage	Ta=+80°C, 240hrs	IEC60068-2-2 GB2423.2
4	Low Temperature Storage		IEC60068-2-1 GB2423.1
5	High Temperature & High Humidity Storage	+40℃, 90% RH max,240 hours	Note2 IEC60068-2-78 GB/T2423.3
6	Thermal Shock (Non-operation)	-30°C 30 min~+70°C 30 min, Change time:5min, 20 Cycle	Start with cold temperature, End with high temperature, IEC60068-2-14,GB2423.22
7	Electro Static Discharge (Operation)	C=150pF, R=330 $\Omega$ , 5points/panel Air:± 8KV, 5times; Contact:± 4KV, 5 times; (Environment: 15 $^{\circ}$ C $^{\circ}$ 35 $^{\circ}$ C, 30% $^{\circ}$ 60%, 86Kpa $^{\circ}$ 106Kpa)	IEC61000-4-2 GB/T17626.2
8	(Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 1 hours for each direction of X.Y.Z.(3 hours for total)	IEC60068-2-6 GB/T2423.10
9		60G 6ms, $\pm$ X, $\pm$ Y, $\pm$ Z 3times for each direction	IEC60068-2-27 GB/T2423.5
10	Package Drop Test	Height:80 cm, 1 corner, 3 edges, 6 surfaces	IEC60068-2-32 GB/T2423.8

Note1: Ts is the temperature of panel's surface.

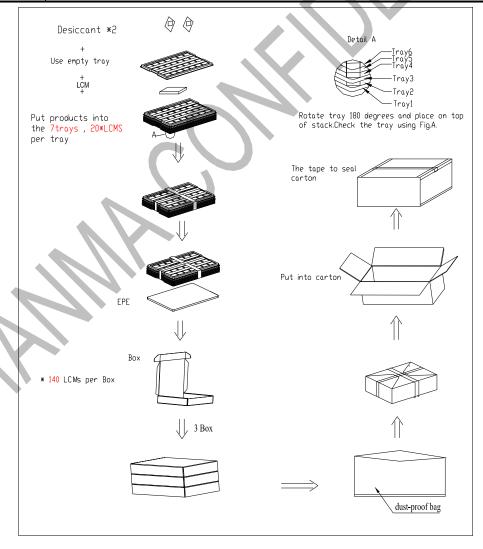
Note2: Ta is the ambient temperature of sample.

## 9 Mechanical drawing



# 10 Packing drawing

No	Item	Model (Material)	Dimensions(mm)	Unit Weight(Kg)	Quantity	Remark
1	LCM module	TM030LDHT1-00	47.28x76.40 x2.40	0.02825	420	
2	Tray	PET(Transmit)	485 x330 x13.8	0.170	24	Anti-stati c
3.	EPE	EPE	485 x330 x5	0.183	3	
4	Anti-static bag	PE	700x545	0.046	1	
5	BOX	Corrugated Paper	520x345x70	0.3879	3	
6	Desiccant	Desiccant	45 x35	0.002	6	
7	Carton	Corrugated Paper	530x351x226	1.01	1	
8	Total weight		19.45±5%			



#### 11 Precautions for use of LCD modules

- 11.1Handling Precautions
- 11.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.
- 11.1.2 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.
- 11.1.3 Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.
- 11.1.4 The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.
- 11.1.5 If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:
  - Isopropyl alcohol。
  - Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents
- 11.1.6 Do not attempt to disassemble the LCD Module.
- 11.1.7 If the logic circuit power is off, do not apply the input signals.
- 11.1.8 To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.
- 11.1.8.1 Be sure to ground the body when handling the LCD Modules.
- 11.1.8.2 Tools required for assembly, such as soldering irons, must be properly ground.
- 11.1.8.3 To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.
- 11.1.8.4 The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.
  - 11.2 Storage precautions
- 11.2.1 When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.
- 11.2.2 The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature :  $0^{\circ}$  ~ 40 ° Relatively humidity: ≤80%

- 11.2.3 The LCD modules should be stored in the room without acid, alkali and harmful gas.
  - 11.3 Transportation Precautions:

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.